

IEEE 802.3 Ethernet Working Group
DRAFT Liaison Communication

Source: IEEE 802.3 Working Group ¹

To: Klaus-Holger Otto, OIF Technical Committee Chair
(klaus-holger.otto@nokia.com)

Kimberly Chiu, Project Manager, OIF
(liaisons@oiforum.com)

CC: Konstantinos Karachalios, Secretary, IEEE-SA Standards Board
Secretary, IEEE-SA Board of Governors
(sasecretary@ieee.org)

Paul Nikolich, Chair, IEEE 802 LMSC
(p.nikolich@ieee.org)

Adam Healey, Vice-chair, IEEE 802.3 Ethernet Working Group
(adam.healey@broadcom.com)

Pete Anslow, Secretary, IEEE 802.3 Ethernet Working Group
(panslow@ciena.com)

Beth Kochuparambil, Chair, IEEE P802.3ck Task Force
(edonnay@cisco.com)

From: David Law, Chair, IEEE 802.3 Ethernet Working Group
(dlaw@hpe.com)

Subject: Status of IEEE P802.3ck Task Force

Approval: Agreed to at IEEE 802.3 Interim meeting, Long Beach, CA, Jan. 17, 2019

Dear Mr. Otto and members of the OIF,

Thank you for your liaison letter providing the status of the OIF CEI-112G-VSR-PAM4 project, along with an Implementation Agreement (IA) document (Oif2017.346.07).

IEEE P802.3ck (100 Gb/s, 200 Gb/s, and 400 Gb/s Electrical Interfaces Task Force) is currently developing 100 Gb/s per lane electrical interfaces for chip-to-module, chip-to-chip, electrical backplane, and copper cable, for 100 Gb/s, 200 Gb/s, and 400 Gb/s Ethernet. The meeting materials from our Jan, 2019 interim meeting can be found at: http://www.ieee802.org/3/ck/public/19_01/index.html.

The IEEE P802.3ck Task Force is targeting to adopt baseline specifications by the May, 2019 meeting. We intend to communicate our future progress to you.

¹ This document solely represents the views of the IEEE 802.3 Working Group, and does not necessarily represent a position of the IEEE, the IEEE Standards Association, or IEEE 802

Sincerely,
David Law
Chair, IEEE 802.3 Ethernet Working Group

DRAFT